

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hiroyuki Ushifusa	03/03/2008
Hideyuki Shoji	03/03/2008
Tsukasa Ishii	03/06/2008
Minoru Sato	03/05/2008
Chieko Aizawa	03/05/2008
RECEIVING PARTY DATA	
Name:	Sony Corporation
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo 108-0075
State/Country:	JAPAN
Name:	Olympus Medical Systems Corp.
Street Address:	Shinjuku Monolith, 3-1 Nishi-Shinjuku 2-chome
City:	Shinjuku-ku, Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11566910
CORRESPONDENCE DATA	
Fax Number:	(312)876-7934
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3128768000
Email:	bhannon@sonnenschein.com
Correspondent Name:	SONNENSCHN NATH & ROSENTHAL LLP Wacker
Address Line 1:	Sears Tower
Address Line 2:	P.O. Box #061080

OP \$40.00 11566910

500504022

PATENT
REEL: 020745 FRAME: 0170

Address Line 4: Chicago, ILLINOIS 60606-1080

ATTORNEY DOCKET NUMBER:

09793822-0210

NAME OF SUBMITTER:

David R. Metzger

Total Attachments: 2

source=Koike_0210_Assgmt2#page1.tif

source=Koike_0210_Assgmt2#page2.tif

ASSIGNMENT

WHEREAS, I, as below named inventor, residing at the address stated next to our name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

Printer and Printing Method

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1, Konan, Minato-ku, Tokyo, Japan and OLYMPUS MEDICAL SYSTEMS CORP., a Japanese corporation, with offices at Shinjuku Monolith, 3-1 Nishi-Shinjuku 2-chome, Shinjuku-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its design, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my Attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/566,910; Filing Date: 5 December 2006.

This assignment executed on the dates indicated below.

Ryusuke FURUHASHI

Name of first or sole Inventor

Signature of first or sole Inventor

Kanagawa, Japan

Residence of first or sole Inventor

Execution Date of this Assignment

Masanori TAKAMATSU

Name of second Inventor

Signature of second Inventor

Kanagawa, Japan

Residence of second Inventor

Execution Date of this Assignment

Hiroshi DOHI

Name of third Inventor

Tokyo, Japan

Residence of third Inventor

Signature of third Inventor

Execution Date of this Assignment

Hideki MATSUZAKA

Name of fourth Inventor

Kanagawa, Japan

Residence of fourth Inventor

Signature of fourth Inventor

Execution Date of this Assignment

Hiroyuki USHIFUSA

Name of fifth Inventor

Tokyo, Japan

Residence of fifth Inventor

Hiroyuki Ushifusa

Signature of fifth Inventor

Mar. 3, 2008

Execution Date of this Assignment

Hideyuki SHOJI

Name of sixth Inventor

Kanagawa, Japan

Residence of sixth Inventor

Hideyuki Shoji

Signature of sixth Inventor

Mar. 3, 2008

Execution Date of this Assignment

Tsukasa ISHII

Name of seventh Inventor

Tokyo, Japan

Residence of seventh Inventor

Tsukasa Ishii

Signature of seventh Inventor

Mar. 6, 2008

Execution Date of this Assignment

Minoru SATO

Name of eighth Inventor

Tokyo, Japan

Residence of eighth Inventor

Minoru Sato

Signature of eighth Inventor

Mar. 5, 2008

Execution Date of this Assignment

Chieko AIZAWA

Name of ninth Inventor

Tokyo, Japan

Residence of ninth Inventor

Chieko Aizawa

Signature of ninth Inventor

Mar. 5, 2008

Execution Date of this Assignment